

* All V_{CC} and V_{CCO} pins are NOT tied together on the die.

Warning: All V_{CC} , GND, and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. Logic Diagrams and Pinout Assignments

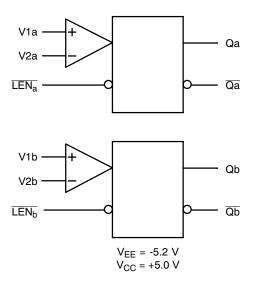


Figure 2. Logic Diagram

Table 1. PIN DESCRIPTION

PIN	FUNCTION					
Qa, Qa	ECL Differential Outputs (a)					
Qb, Qb	ECL Differential Outputs (b)					
LENa, LENb	ECL Latch Enable					
V1a, V1b	Input Comparator 1					
V2a, V2b	Input Comparator 2					
V _{CC}	Positive Supply					
V _{EE}	Negative Supply					
NC	No Connect					
GND	Ground					

Table 2. FUNCTION TABLE

LEN	V1, V2	Function
H	V1 > V2	H
H	V1 < V2	L
L	X	Latched

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{SUP}	Total Supply Voltage	V _{EE} + V _{CC}		12.0	V
V _{PP}	Differential Input Voltage	V1 - V2		3.7	V
VI	Input Voltage			$V_{EE} \le V_I \le V_{CC}$	V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
T _A	Operating Temperature Range			0 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	28 PLCC 28 PLCC	63.5 43.5	°C/W °C/W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	28 PLCC	22 to 26	°C/W
V _{EE}	Operating Range	GND = 0 V		-4.2 to -5.7	V
T _{sol}	Wave Solder Pb Pb-Free	≤ 3 sec @ 248°C ≤ 3 sec @ 260°C		265 265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 4. DC CHARACTERISTICS V_{CC} = +5.0 V ±5%; V_{EE} = -5.2 V ±5%, GND = 0 V (Note 1)

			0°C 25°C			85°C					
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
V _{OH}	Output HIGH Voltage (Note 1)	-1020		-840	-980		-810	-920		-735	mV
V _{OL}	Output Low Voltage (Note 1)	-1950		-1630	-1950		-1630	-1950		-1600	mV
V _{IL}	Input LOW Voltage (LEN) (Note 1)	-1.95		-1.48	-1.95		-1.48	-1.95		-1.45	mV
V _{IH}	Input HIGH Voltage (LEN) (Note 1)	-1.17		-0.84	-1.13		-0.81	-1.07		-0.735	mV
II I _{IH}	Input Current (V1, V2) Input HIGH Current (LEN)			65 150			65 150			65 150	μΑ
I _{CC} I _{EE}	Positive Supply Current Negative Supply Current			50 -55			50 -55			50 -55	mA
VCMR	Common Mode Range (Note 2)	-2.0		3.0	-2.0		3.0	-2.0		3.0	٧
Hys	Hysteresis		27			27			30		mV
V _{skew}	Hysteresis Skew (Note 3)		-1.0			-1.0			0		mV
C _{in}	Input Capacitance DI PLC			3 2			3 2			3 2	pF

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input V_{IL} and V_{IH} parameters vary 1:1 with V_{CC} . Output V_{OH} and V_{OL} parameters vary 1:1 with GND.
- 2. VCMR Min varies 1:1 with V_{EE}; Max varies 1:1 with V_{CC}.
- 3. Hysteresis skew (V_{skew}) is provided to indicate the offset of the hysteresis window. For example, at 25°C the nominal hysteresis value is 27 mV and the V_{skew} value indicates that the hysteresis was skewed from the reference level by 1mV in the negative direction. Hence the hysteresis window ranged from 14 mV below the reference level to 13 mV above the reference level. All hysteresis measurements were determined using a reference voltage of 0 mV.

Table 5. AC CHARACTERISTICS $V_{CC} = +5.0 \text{ V} \pm 5\%$; $V_{EE} = -5.2 \text{ V} \pm 5\%$, GND = 0 V (Note 4)

			0°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{MAX}	Maximum Toggle Frequency		TBD			> 1.0			TBD		GHz
t _{PLH} t _{PHL}	Propagation Delay to Output (Note 4) V to Q LEN to Q	750 550	900 725	1050 900	775 550	925 750	1075 900	850 650	1025 825	1200 1000	ps
ts	Setup Time V	450	300		450	300		550	350		ps
t _h	Enable Hold Time V	-50	-250		-50	-250		-100	-250		ps
t _{pw}	Minimum Pulse Width LEN	400			400			400			ps
t _{skew}	Within Device Skew (Note 5)		15			15			15		ps
t _{JITTER}	Cycle-to-Cycle Jitter		TBD			TBD			TBD		ps
T _{DE}	Delay Dispersion (ECL Levels) (Notes 6, 7) (Notes 6, 8)					100 60					ps
T _{DL}	Delay Dispersion (TTL Levels) (Notes 9, 10) (Notes 8, 9)					350 100					ps
t _r t _f	Rise/Fall Times (20-80%)	225	325	475	225	325	475	250	375	500	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 4. Input V_{IL} and V_{IH} parameters vary 1:1 with V_{CC} , output V_{OH} and V_{OL} parameters vary 1:1 with GND.
- 5. t_{skew} is the propagation delay skew between comparator A and comparator B for a particular part under identical input conditions.
- 6. Refer to figure 4 and note that the input is at 850mV ECL levels with the input threshold range between the 20% and 80% points. The delay is measured from the crosspoint of the input signal and the threshold value to the crosspoint of the Q and Q output signals.
- 7. The slew rate is 0.25 V/NS for input rising edges.
- 8. The slew rate is 0.75 V/NS for input rising edges.
- 9. Refer to Figure 5 and note that the input is at 2.5 V TTL levels with the input threshold range between the 20% and 80% points. The delay is measured from the crosspoint of the input signal and the threshold value to the crosspoint of the Q and Q output signals.
- 10. The slew rate is 0.3 V/NS for input rising edges.

APPLICATIONS INFORMATION

The timing diagram (Figure 3.) is presented to illustrate the MC10E1651's compare and latch features. When the signal on the LEN pin is at a logic high level, the device is operating in the "compare mode," and the signal on the input arrives at the output after a nominal propagation delay (tPHL, t_{PLH}). The input signal must be asserted for a time, t_s, prior to the negative going transition on LEN and held for a time, th, after the LEN transition. After time th, the latch is operating in the "latch mode," thus transitions on the input do not appear at the output. The device continues to operate in the "latch mode" until the latch is asserted once again. Moreover, the \overline{LEN} pulse must meet the minimum pulse width (t_{pw}) requirement to effect the correct input-output relationship. Note that the $\overline{\text{LEN}}$ waveform in Figure 3. shows the LEN signal swinging around a reference labeled VBB_{INT}; this waveform emphasizes the requirement that LEN follow typical ECL 10KH logic levels because

 VBB_{INT} is the internally generated reference level, hence is nominally at the ECL V_{BB} level.

Finally, V_{OD} is the input voltage overdrive and represents the voltage level beyond the threshold level (V_{THR}) to which the input is driven. As an example, if the threshold level is set on one of the comparator inputs as 80 mV and the input signal swing on the complementary input is from zero to 100 mV, the positive going overdrive would be 20 mV and the negative going overdrive would be 80 mV. The result of differing overdrive levels is that the devices have shorter propagation delays with greater overdrive because the threshold level is crossed sooner than the case of lower overdrive levels. Typically, semiconductor manufactures refer to the threshold voltage as the input offset voltage (VOS) since the threshold voltage is the sum of the externally supplied reference voltage and inherent device offset voltage.

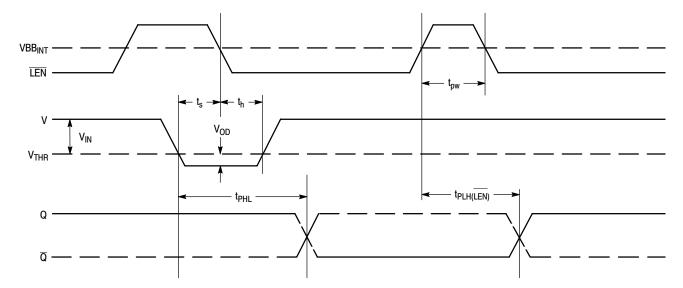


Figure 3. Input/Output Timing Diagram

DELAY DISPERSION

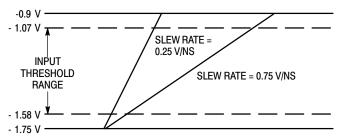
Under a constant set of input conditions comparators have a specified nominal propagation delay. However, since propagation delay is a function of input slew rate and input voltage overdrive the delay dispersion parameters, T_{DE} and T_{DT} , are provided to allow the user to adjust for these variables (where T_{DE} and T_{DT} apply to inputs with standard ECL and TTL levels, respectively).

Figure 4 and Figure 5 define a range of input conditions which incorporate varying input slew rates and input voltage overdrive. For input parameters that adhere to these constraints the propagation delay can be described as:

$$T_{NOM} \pm T_{DE}$$
 (or T_{DT})

where T_{NOM} is the nominal propagation delay. T_{NOM} accounts for nonuniformity introduced by temperature and voltage variability, whereas the delay dispersion parameter takes into consideration input slew rate and input voltage overdrive variability. Thus a modified propagation delay can be approximated to account for the effects of input conditions that differ from those under which the parts where tested. For example, an application may specify an ECL input with a slew rate of 0.25 V/NS, an overdrive of 17 mV and a temperature of 25°C, the delay dispersion parameter would be 100 ps. The modified propagation delay would be

 $775 \text{ ps} \pm 100 \text{ ps}$



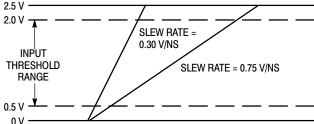


Figure 4. ECL Dispersion Test Input Conditions

Figure 5. TTL Dispersion Test Input Conditions

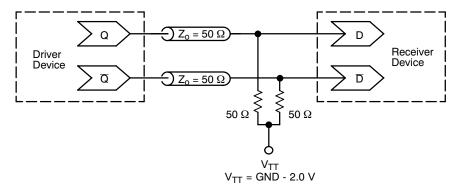


Figure 6. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D - Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping [†]
MC10E1651L	CDIP-16	25 Units / Rail
MC10E1651FN	PLCC-20	46 Units / Rail
MC10E1651FNG	PLCC-20 (Pb-Free)	46 Units / Rail
MC10E1651FNR2	PLCC-20	500 / Tape & Reel
MC10E1651FNR2G	PLCC-20 (Pb-Free)	500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1672/D - The ECL Translator Guide

AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

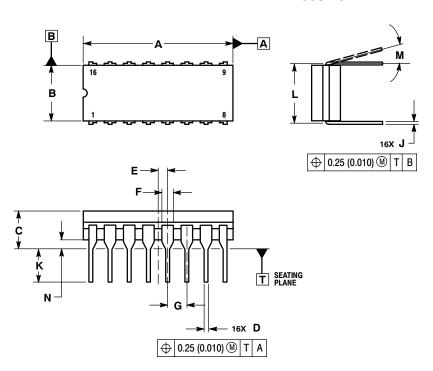
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

CDIP-16 L SUFFIX CERAMIC DIP PACKAGE CASE 620A-01 ISSUE O



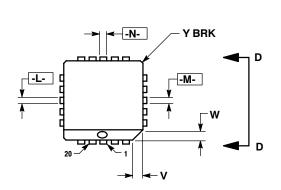
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L'TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.
 5. THIS DRAWING REPLACES OBSOLETE CASE OUTLINE 620-10.

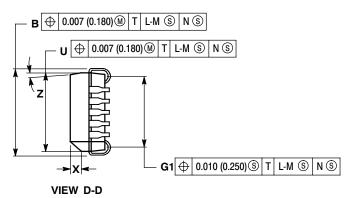
	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
Е	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300 BSC		7.62	BSC	
M	0°	15°	0°	15°	
N	0.020	0.040	0.51	1.01	

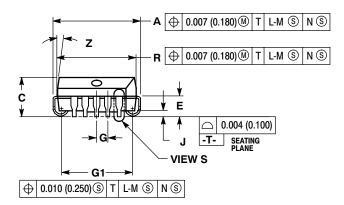
PACKAGE DIMENSIONS

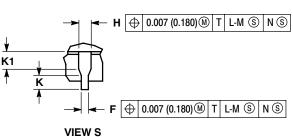
20 LEAD PLLC

CASE 775-02 **ISSUE E**









- NOTES:
 1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M,
- 1982.
 2. DIMENSIONS IN INCHES.
 3. DATUMS -L., -M., AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD

- OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

 4. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM .-T., SEATING PLANE.

 5. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

 6. DIMENSIONS IN THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

 7. DIMENSION H DOES NOT INCLUDE DAMBAR
- PLASTIC BODY.

 DIMENSION H DOES NOT INCLUDE DAMBAR
 PROTRUSION OR INTRUSION. THE DAMBAR
 PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION
 TO BE GREATER THAN 0.037 (0.940). THE DAMBAR
 INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO
 BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.385	0.395	9.78	10.03	
В	0.385	0.395	9.78	10.03	
С	0.165	0.180	4.20	4.57	
E	0.090	0.110	2.29	2.79	
F	0.013	0.019	0.33	0.48	
G	0.050	BSC	1.27	BSC	
Н	0.026	0.032	0.66	0.81	
J	0.020		0.51		
K	0.025		0.64		
R	0.350	0.356	8.89	9.04	
U	0.350	0.356	8.89	9.04	
V	0.042	0.048	1.07	1.21	
W	0.042	0.048	1.07	1.21	
Х	0.042	0.056	1.07	1.42	
Υ		0.020		0.50	
Z	2 °	10°	2 °	10 °	
G1	0.310	0.330	7.88	8.38	
K1	0.040		1.02		

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